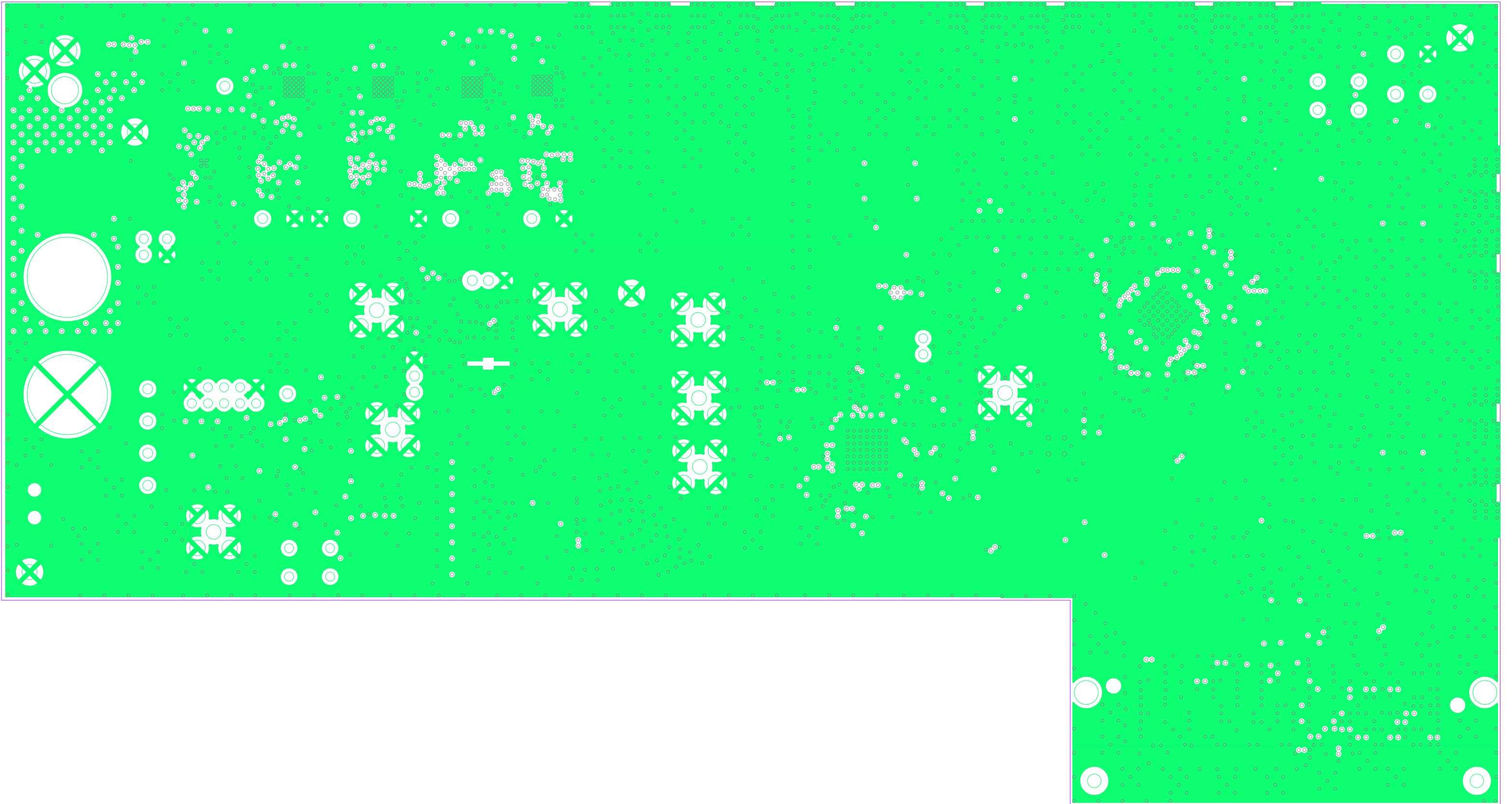


ADS58J89/ADS54J54 REV C  
COMPONENT SIDE LAYER 1

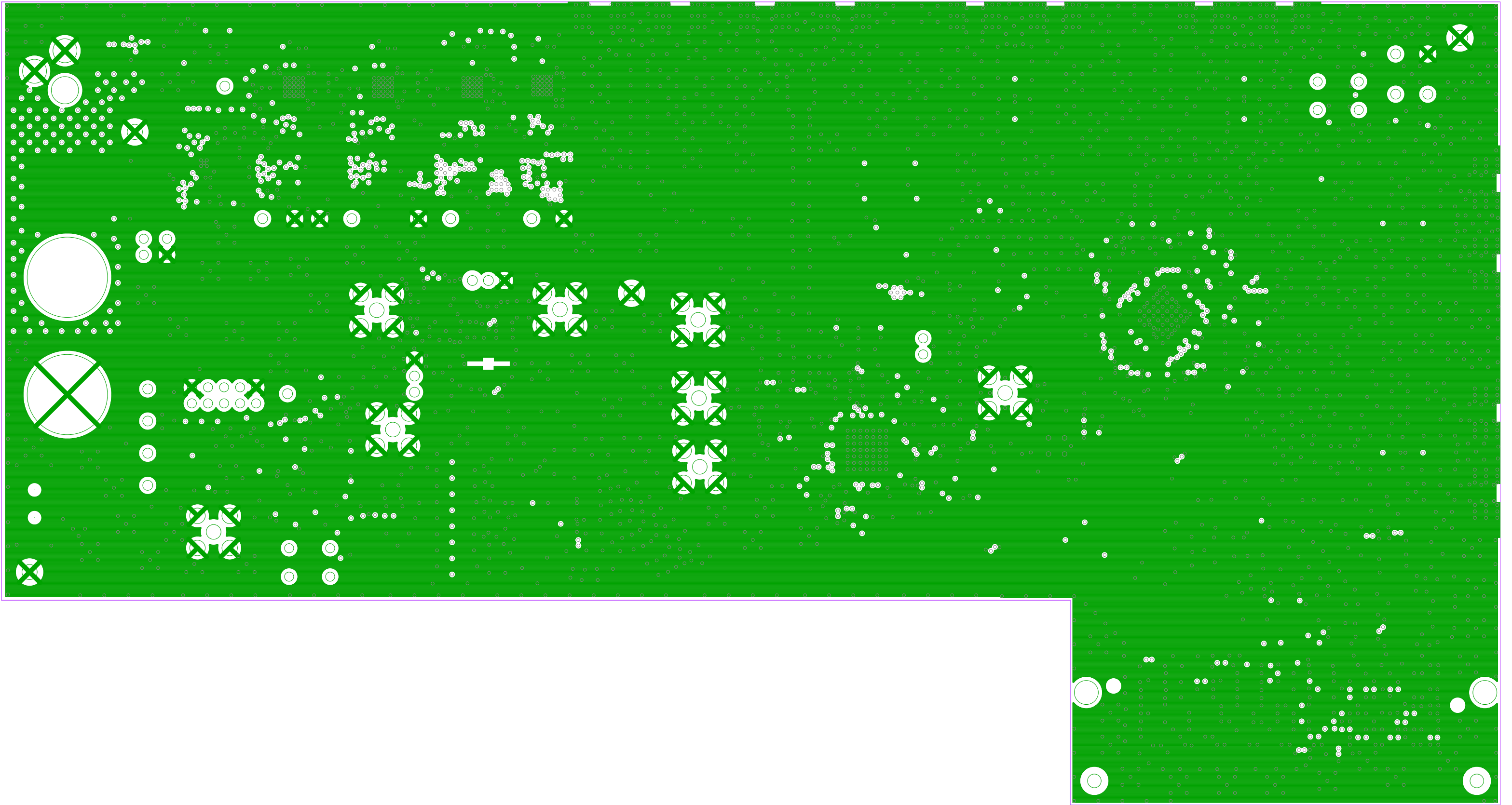


ADS58J89/ADS54J54 REV C

LAYER 2 (GND1)

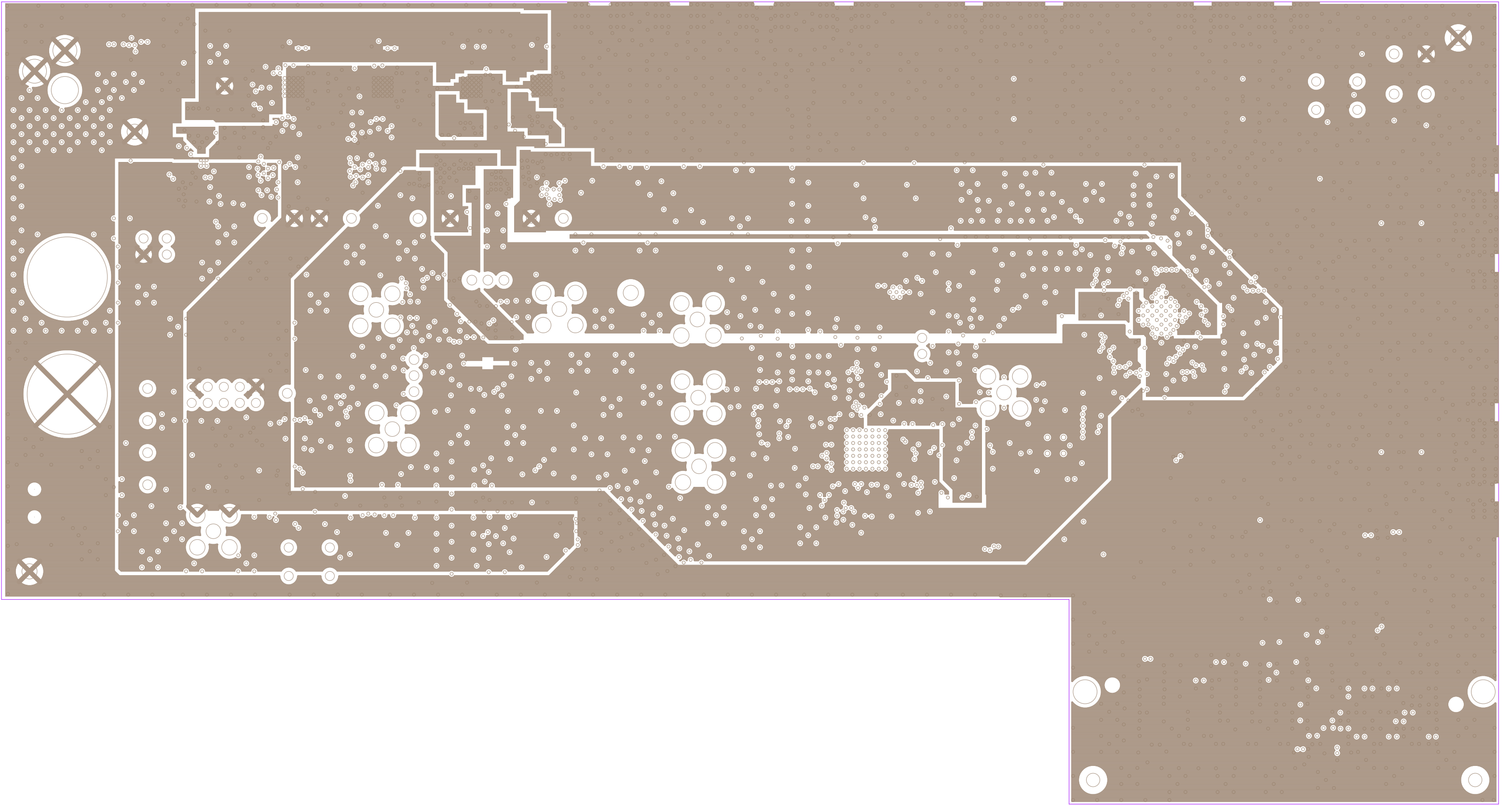




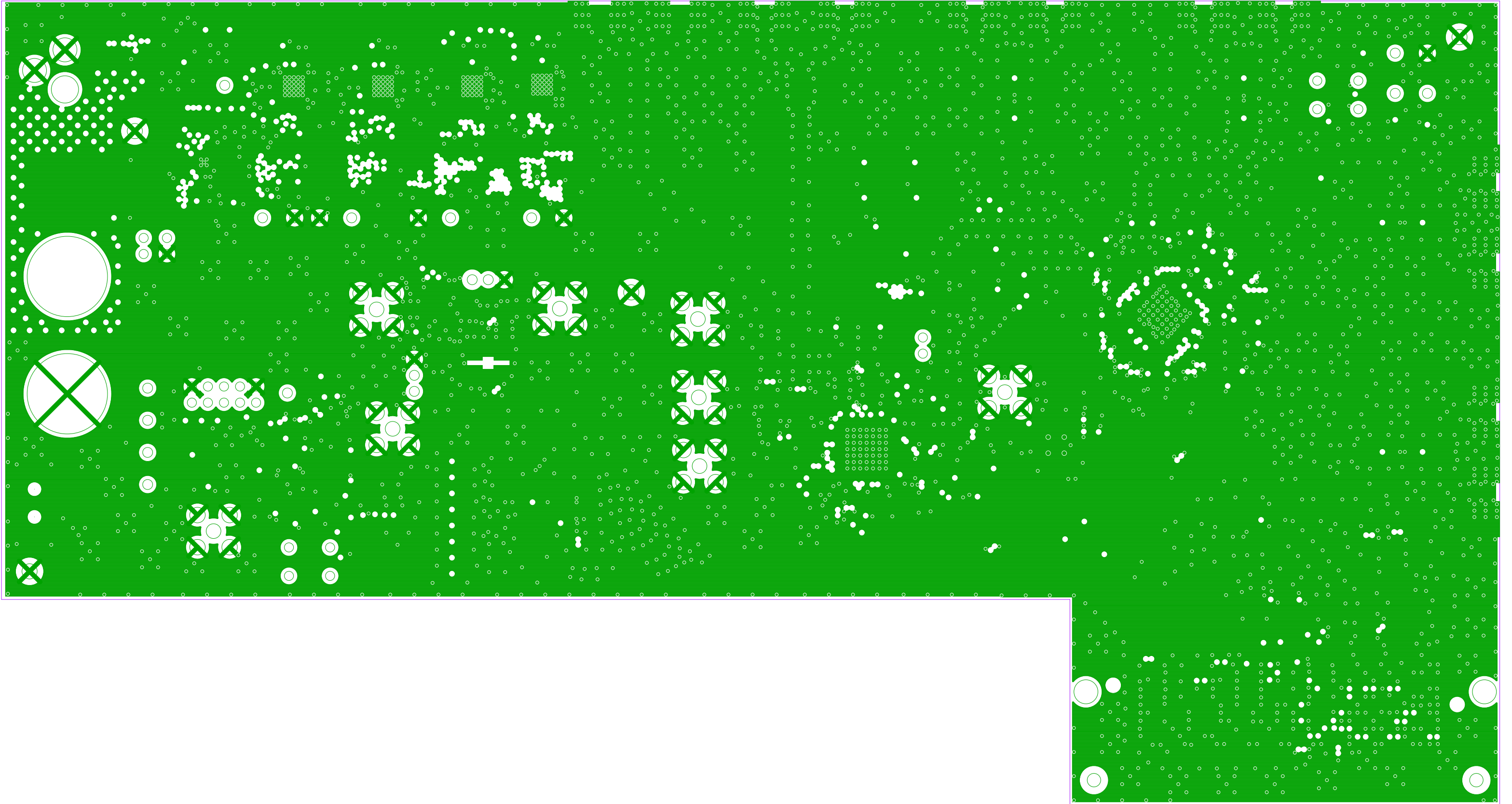


ADS58J89/ADS54J54 REV C

LAYER 4 (GND2)



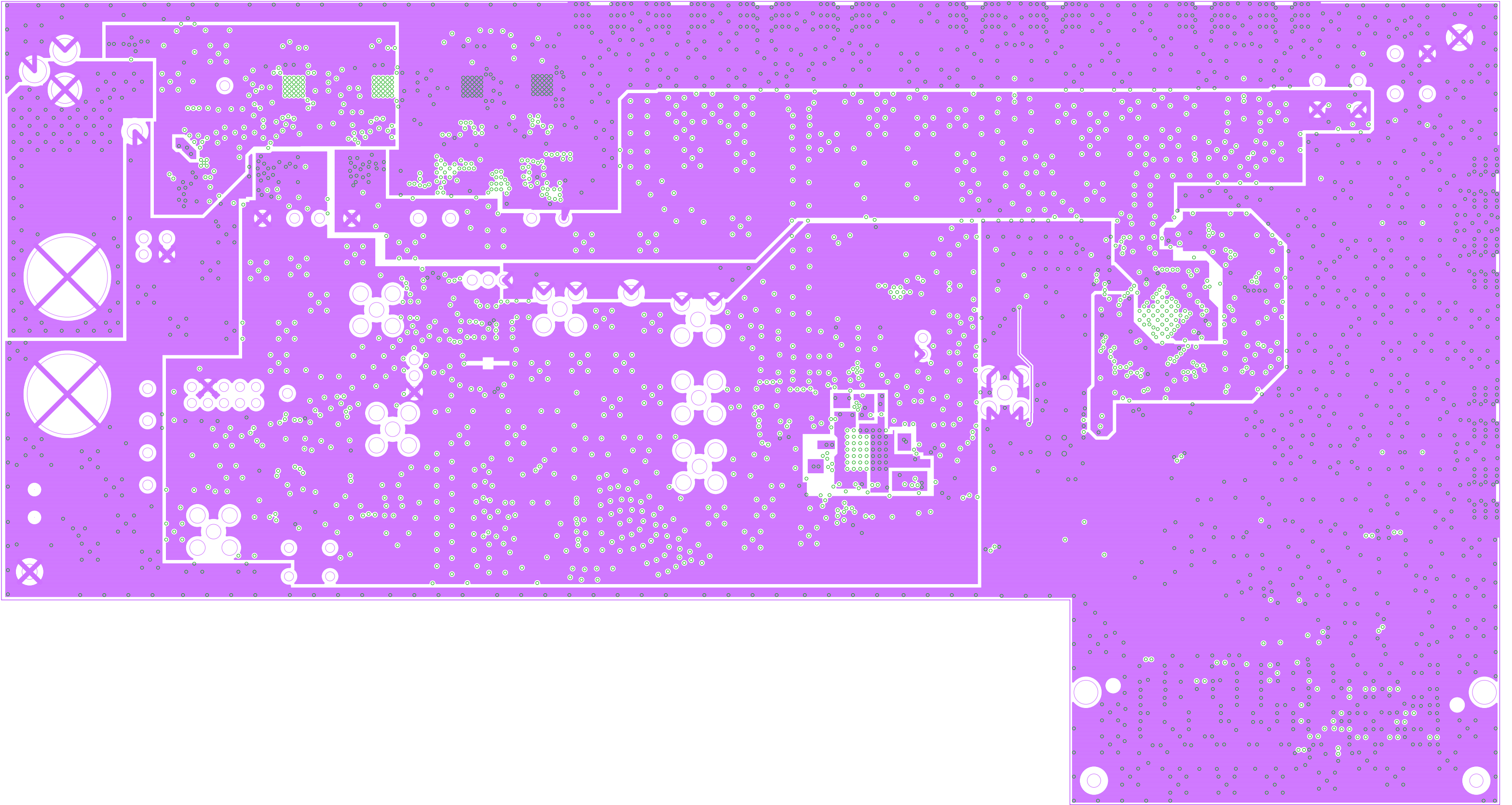
ADS58J89/ADS54J54 REV C  
LAYER 5 ( PWR1.8V )



ADS58J89/ADS54J54 REV C

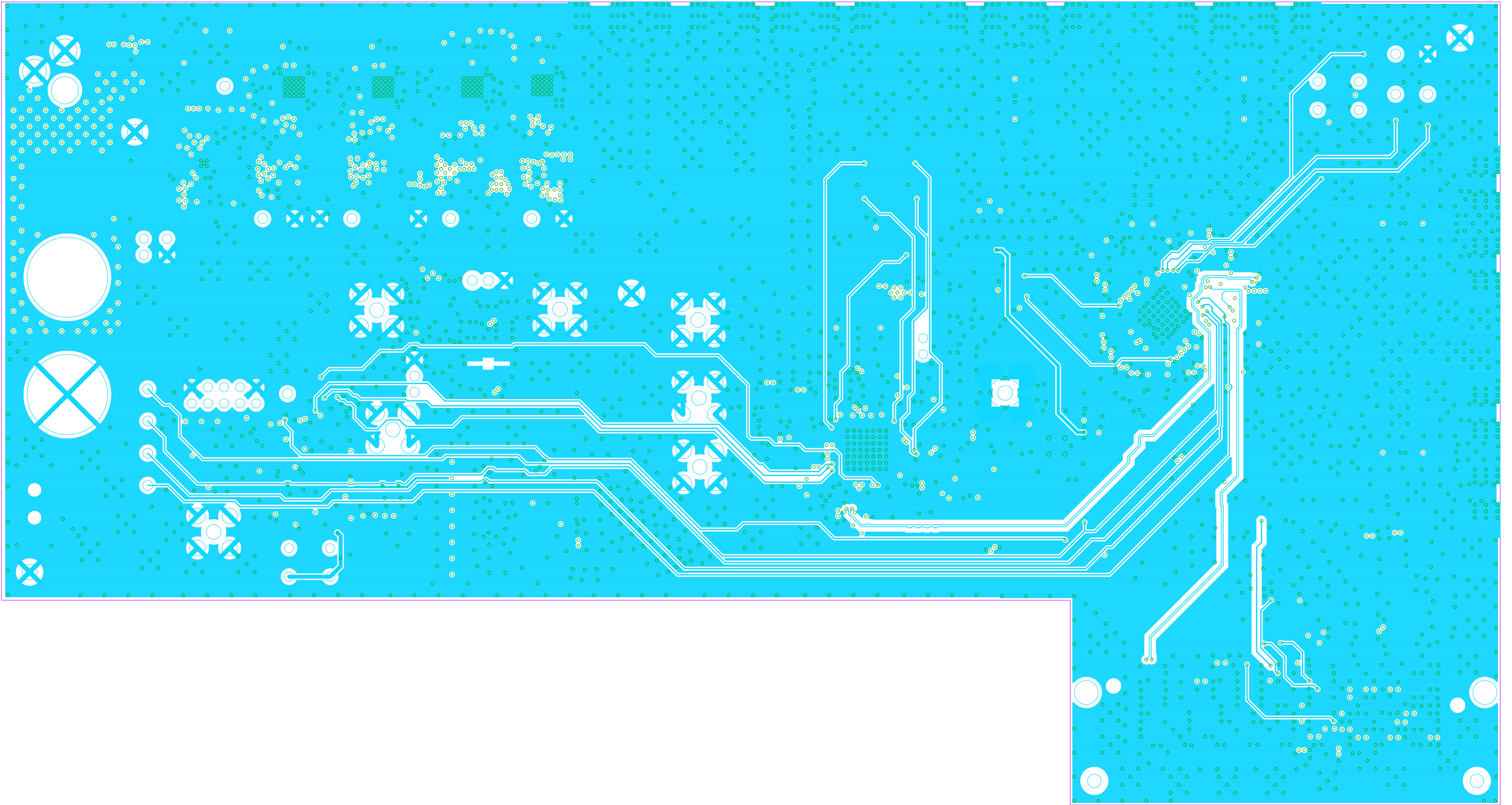
LAYER 6 (GND3)





ADS58J89/ADS54J54 REV C

LAYER 7 (PWR2)



ADS58J89/ADS54J54 REV C

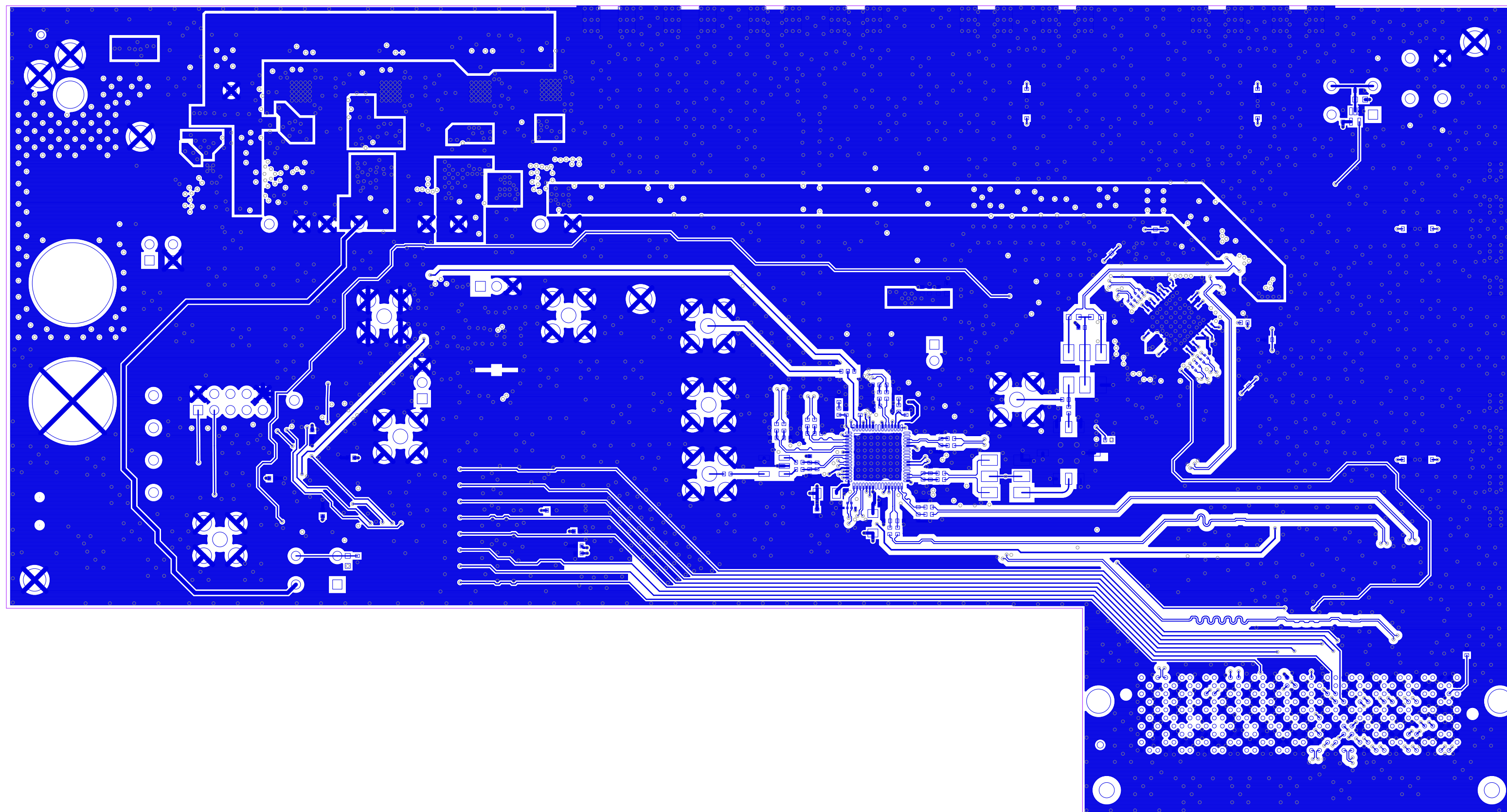
LAYER 8 (SIG)





ADS58J89/ADS54J54 REV C

LAYER 9 (GND4)

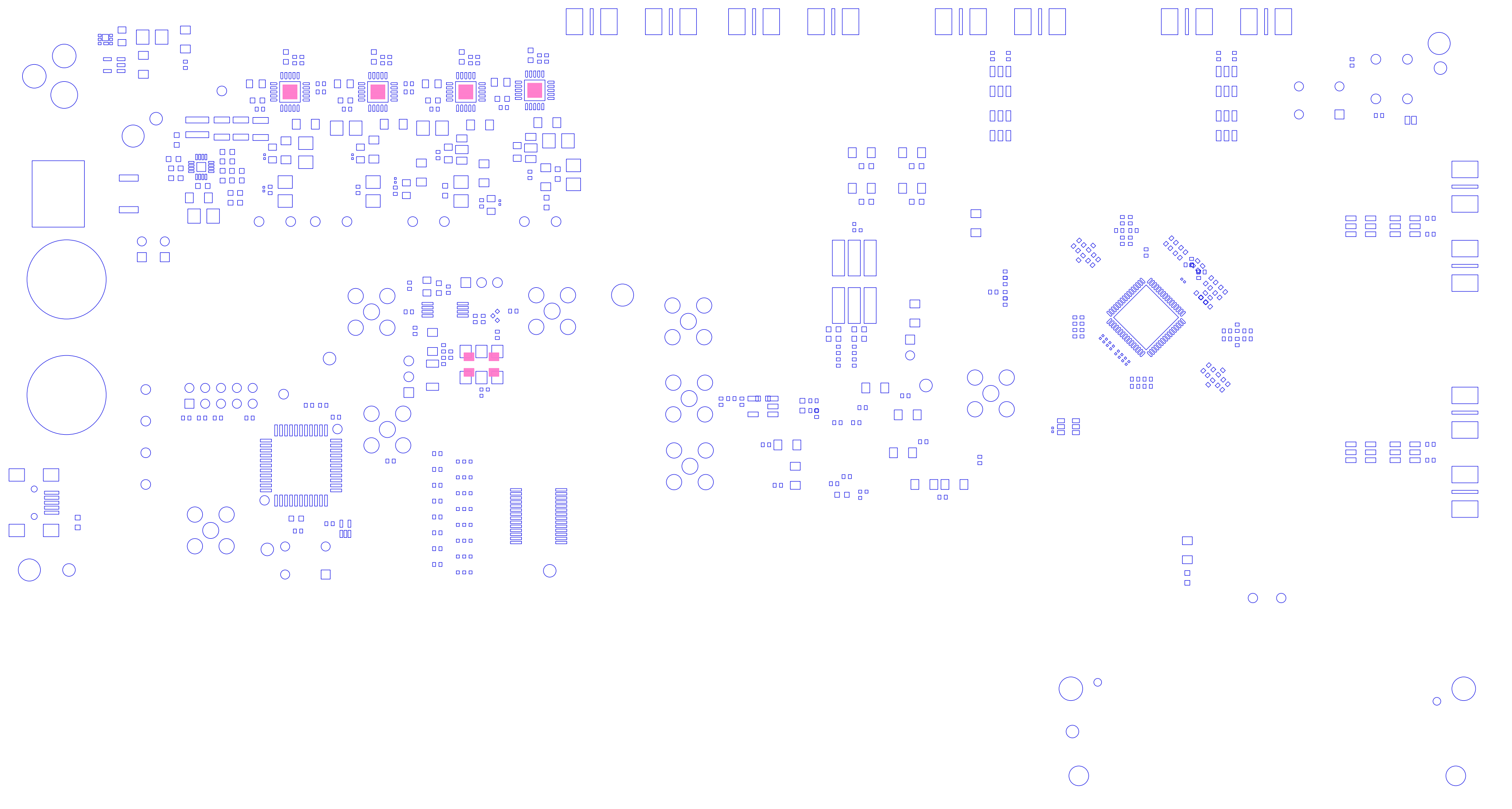


ADS58J89/ADS54J54 REV C  
BOTTOM SIDE LAYER 10



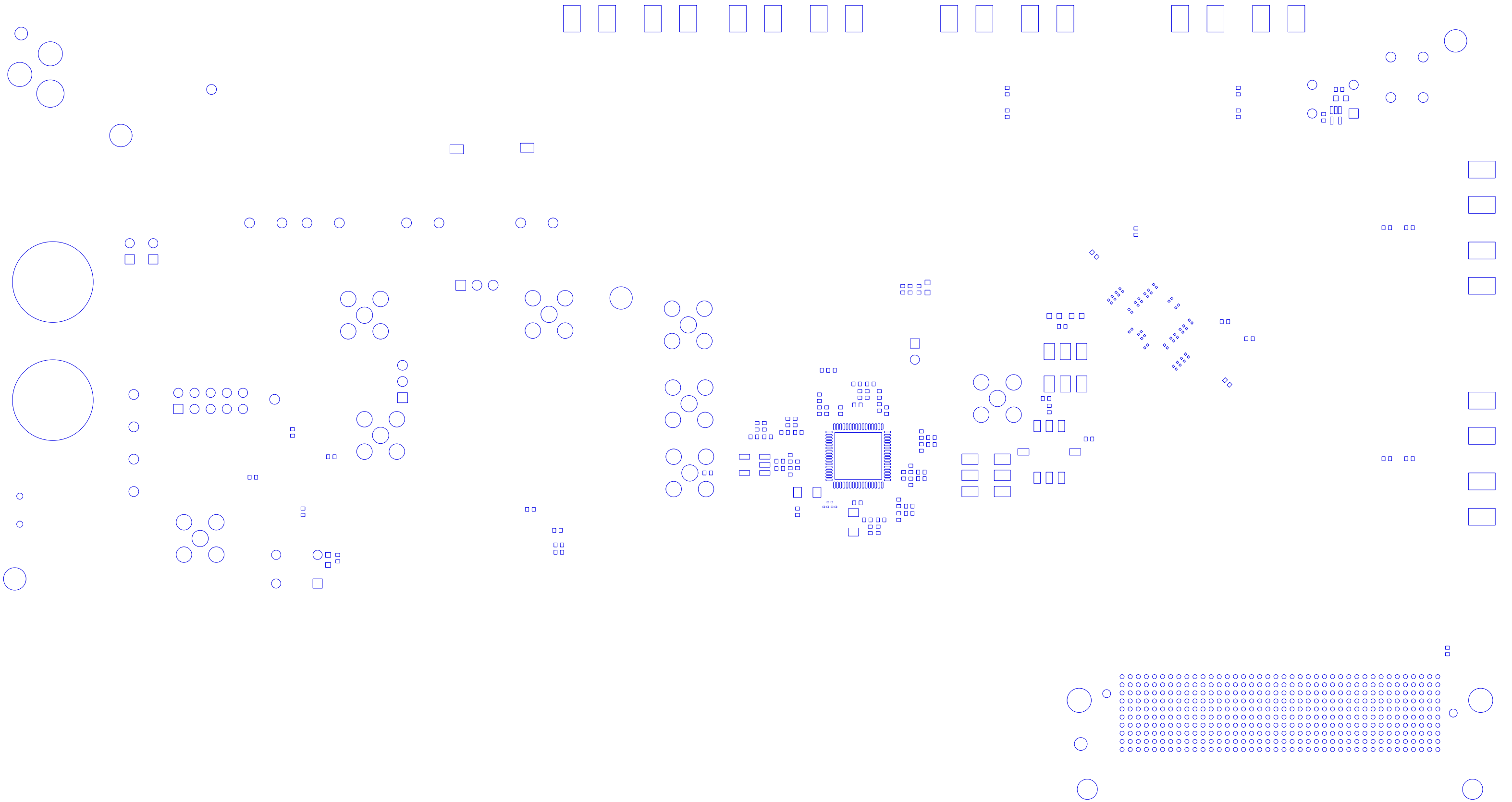






ADS58J89/ADS54J54 REV C

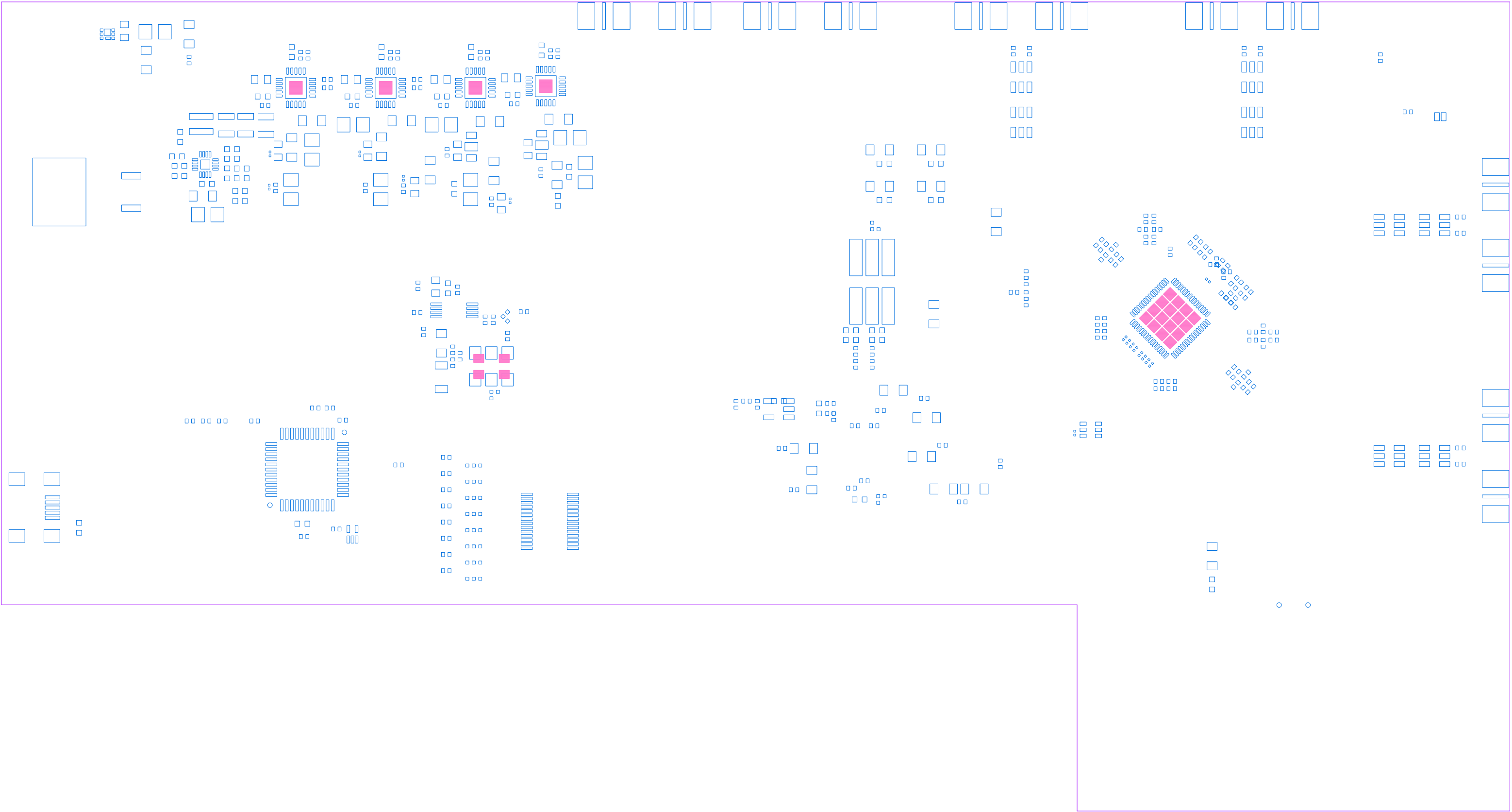
SOLDERMASK TOP



ADS58J89/ADS54J54 REV C

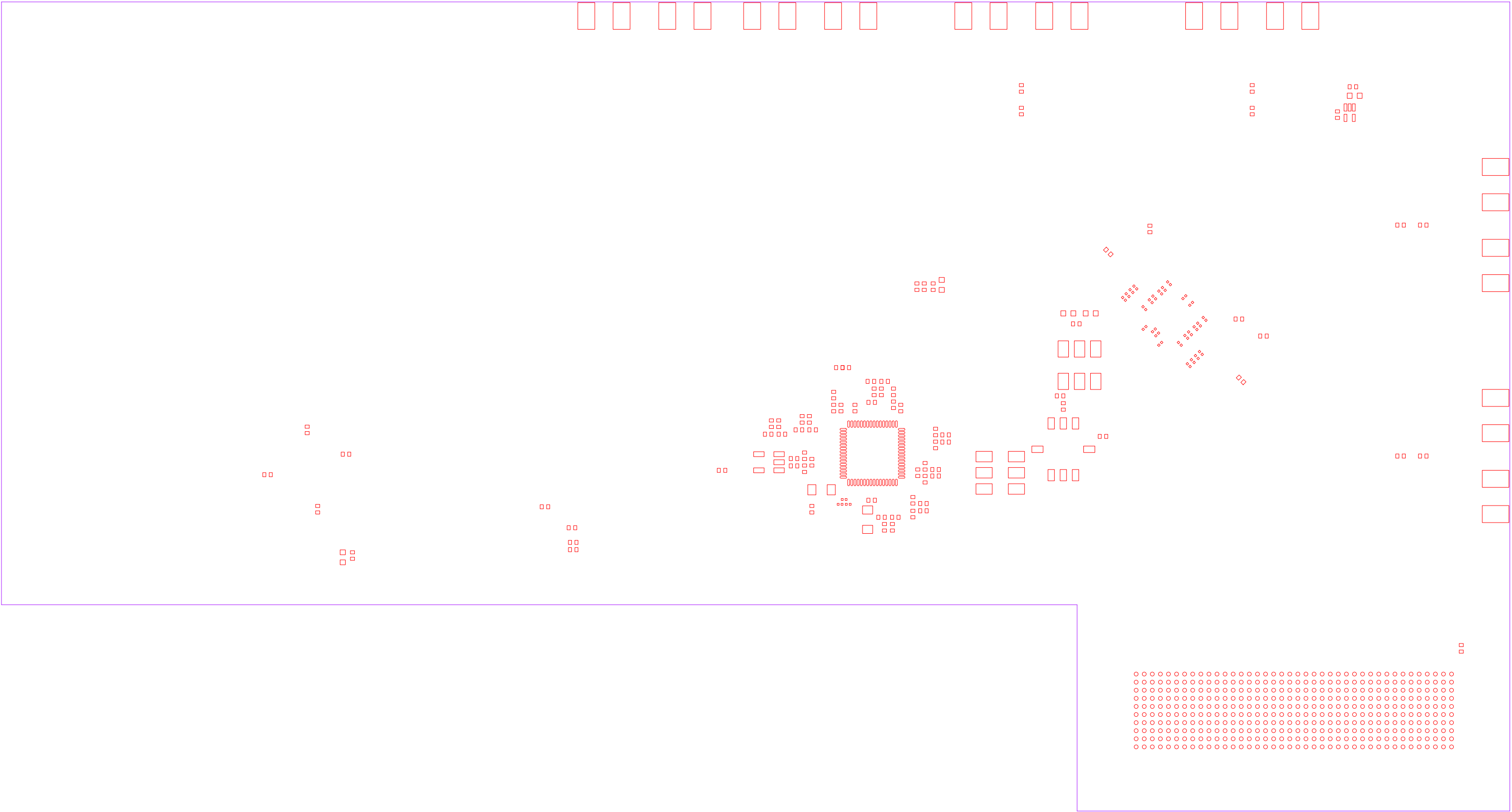
SOLDERMASK BOTTOM





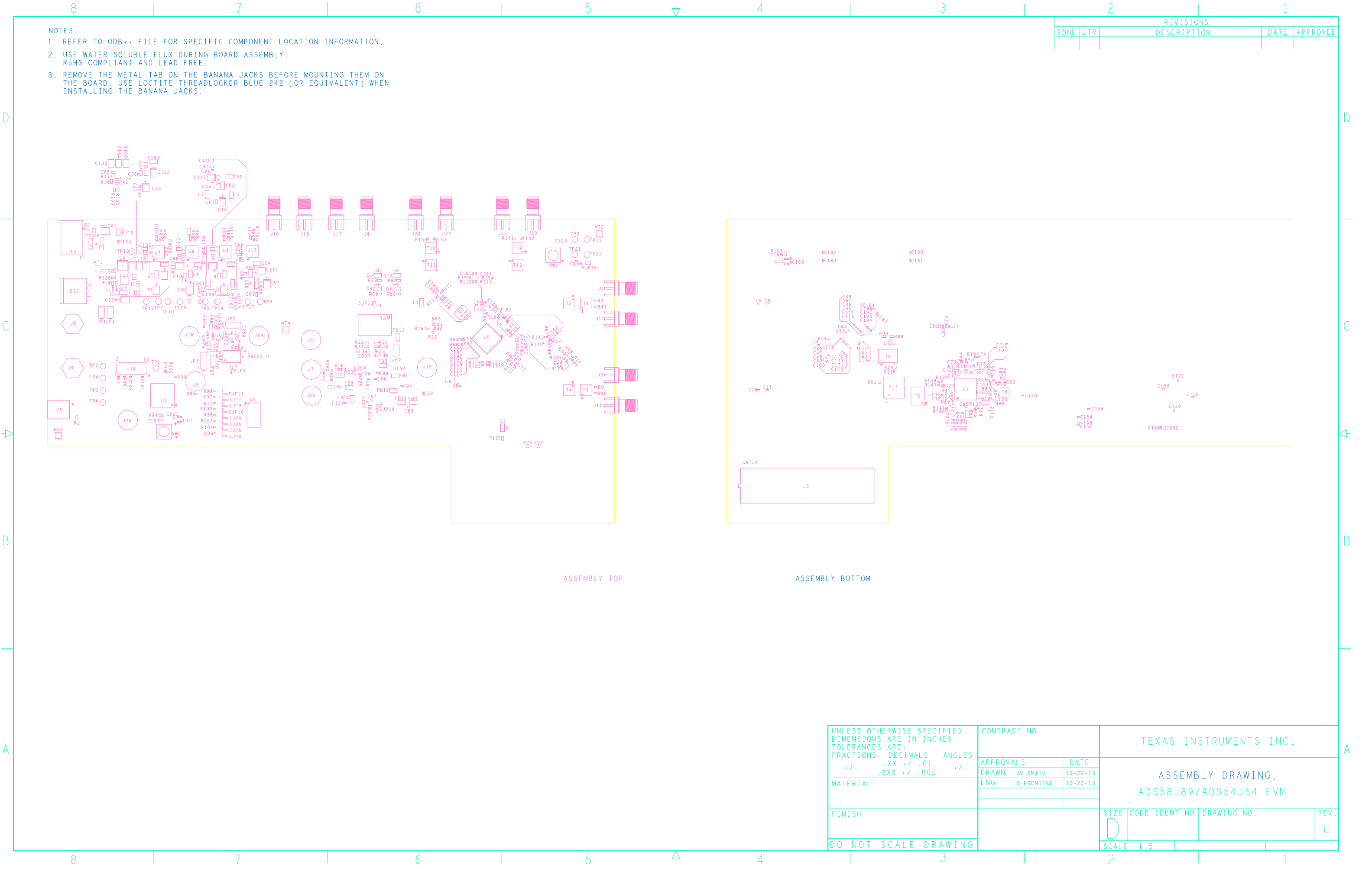
ADS58J89/ADS54J54 REV C

PASTEMASK TOP



ADS58J89/ADS54J54 REV C

PASTEMASK BOTTOM



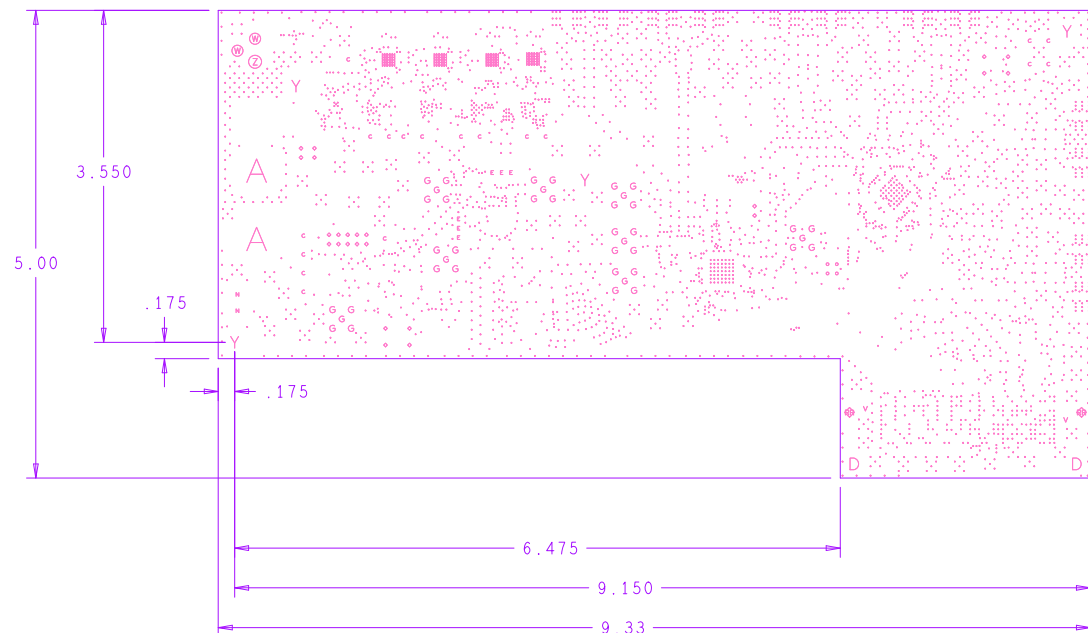


UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.  
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.  
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.  
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
2. VIAS, 10 & 12mil HOLES, SIZE APPLY AFTER PLATING. TOLERANCE TO BE  $\pm .003/- .010$ .  
HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE  $\pm/- .003$ .
3. REGISTRATION TOLERANCE: ARTWORK  $\pm/- .002$ .  
ALL HOLE CENTERS  $\pm/- .005$  FROM DIMENSION DATUM.
4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.  
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.  
MATERIAL: MULTI-LAYER (SEE DETAIL 'A')  
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062  $\pm/- 10\%$
6. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
7. SMOBC/IMMERSION GOLD: 2 - 8 uIN OVER 118-236 uIN NICKEL PLATING.
8. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT)  
COLOR = RED (0.001 TO .002" THICK OVER METAL.
9. SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.  
REGISTRATION TOLERANCE TO BE  $\pm/- .005$ .  
INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
10. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
11. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
12. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

13. ALL OUTER LAYERS USING 8.7MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED +/- 10%.
14. ALL OUTER LAYERS USING A 5.6MIL TRACE WIDTH AND 6.4MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL +/- 10%.  
ALL INNER LAYERS USING 5MIL TRACE WIDTH AND 7MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL +/- 10%.
15. MINIMUM COPPER CONDUCTOR WIDTH IS: 4.5MIL.  
MINIMUM COPPER CONDUCTOR SPACING IS: 4.5MIL.
16. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
17. PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY,  
MAX REFLOW OF 260 DEGREES C (6 PASSES).
18. COPPER TO THE BOARD EDGE IS INTENTIONAL. DO NOT CUT IT BACK.

USE VIASYSTEMS STACKUP PART NUMBER AD58J8X-10



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
A	10.0	PLATED	3477
B	12.0	PLATED	100
C	20.0	PLATED	4
D	38.0	PLATED	18
E	38.0	PLATED	24
F	40.0	PLATED	6
G	62.0	PLATED	8
H	67.0	PLATED	32
I	106.0	PLATED	2
J	120.0	PLATED	2
K	125.0	PLATED	4
L	140.0	PLATED	1
M	250.0	PLATED	2
N	39.0	NON-PLATED	2
O	50.0	NON-PLATED	2
P	125.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS    DECIMALS    ANGLES +/-                   .XX +/- .01                   +/- .XXX +/- .005                   +/-		CONTRACT NO.		TEXAS INSTRUMENTS INC.			
MATERIAL  SEE NOTE 5		APPROVALS		DATE		FABRICATION DRAWING ADS58J89/ADS54J54 EVM	
		DRAWN    JV SMITH		10-22-13			
		ENG        R PRENTICE		10-22-13			
FINISH  SEE NOTE 7, 8, 9				SIZE	CODE IDENT NO.	DRAWING NO.	REV.
DO NOT SCALE DRAWING				D			C
				SCALE	1. NONE		SHEET 1 OF 1